

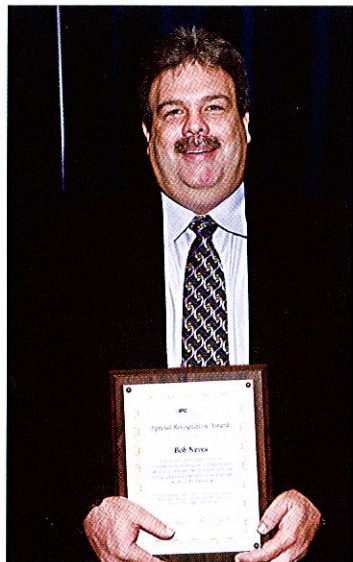


ReVIEW

Vol. 1, No 1: March/April 2008

IPC Hall of Fame AWARD

Robert Neves To Receive IPC's 2007 Hall Of Fame Award



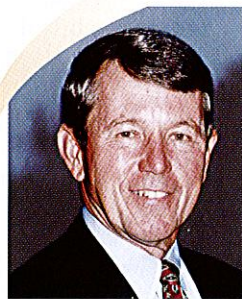
Bob Neves

IPC will honor Robert (Bob) Neves, chairman and chief technology officer of Microtek Laboratories, with the 2007 IPC Raymond E. Pritchard Hall of Fame Award at the 2008 IPC Printed Circuits Expo®, APEX® and the Designers Summit on April 1 in Las Vegas. Based on exceptional lifetime achievement, the Raymond E. Pritchard Hall of Fame Award is IPC's highest level of recognition, honoring members who make extraordinary contributions to IPC and the electronic interconnect industry.

Neves has been active in IPC since 1986 and been an important participant in nearly 50 committees. As a board member with the California Circuits Association (CCA), Neves was instrumental in CCA's joining with IPC in 1996, ultimately serving as the first chairman of the IPC/CCA Council. Starting his IPC service leading the Lab Qualifications (IPC-QL-653) Task Group, he was singled out in 1992 for the position of chairman of the Rigid Printed Boards Committee and served nine years in that role. Recipient of the IPC Presidents Award in 1996, Neves chaired the High Density Interconnect (HDI) Committee from 1997 to 2005. Since 1992, Neves has participated in several subcommittees of IPC's highest policy group for standards activities, the IPC Technical Activities Executive Committee (TAEC), chairing the group from 2004-2006. Neves recalls, "I started attending meetings in 1986 and haven't missed a major IPC event since. I can say that the friendships I have made and the bonds forged through my IPC participation mean the most to me."

Continued on page 5

Between the LINES



Innovation: Isn't This What We're All About?

Creativity is thinking up new things. Innovation is doing new things.

*Theodore Leavitt,
Economist and Harvard
Business School Professor*

In order to stay ahead in this industry, you need to be creative, innovative and always thinking outside the box. Same with communication. What worked a decade ago may not cut it today. What you see before you marks a change for the 49-year-old *IPC Review*. The content and design have been revamped and reformatted to bring IPC's decades-old member magazine into the 21st century. We'll now issue the *Review* bi-monthly in a 12-page newsletter format. Tried and true features will still be available though, including news items, technical articles, upcoming events, government and EHS updates, status of standardization and features.

In January, we unveiled our online portal (found on IPC's home page) with technical articles, webcasts and podcasts. From the responses so far, you're liking what you see.

As always, we look forward to your feedback on the communication pieces we send your way. We hope we can always stay ahead of the innovation curve by constantly creating new, yet effective ways to reach out to our membership and industry in general. And speaking of innovation, I wanted to extend an invitation to IPC Printed Circuits Expo®, APEX® and the Designers Summit. Just as this publication is designed with you in mind, the April tradeshow is designed to bring you the latest information on electronic manufacturing and technology, networking opportunities and more.

Creativity brings on innovation. Help spread the word. ◀

In This ISSUE

- 1 Hall of Fame Winner Announced
- 1 Between the Lines
- 2 Corporate Recognition Award Winners
- 3 IPC News
- 6 Feature Articles Now Live on IPC's Home Page
- 7 IPC Printed Circuits Expo, APEX and the Designers Summit Schedule at a Glance

- 7 Status of Standardization
- 8 Technical Article — Lead-Free Compatible Base Materials
- 10 Government Relations Update — R&D Tax Credit and RoHS
- 11 EHS Update — RoHS, REACH and You
- 12 Upcoming Events

Online Exclusive: Identification of Assembly and Soldering Defects Today — History Tomorrow
by **Bob Willis**, Electronic Presentation Services

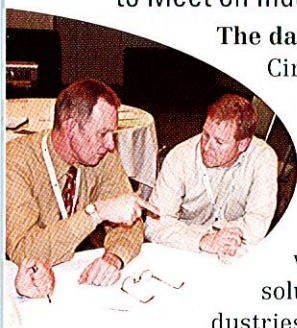
comments. EPA acknowledged that some of the proposed ICR changes could have been proposed through the notice-and-comment rulemaking process therefore certain proposed form changes were excluded from the revised ICR. IPC will continue to work with EPA to represent member interests and to improve data collection under the TRI Program.

IPC's full comments (as a PDF file) can be viewed at www.IPC.org/TRI-ICR-Comments.

Management Meetings

Leaders of PCB and EMS Companies to Meet on Industry Issues

The day before IPC Printed Circuits Exp[®], APEX[®] and the Designers Summit opens in Las Vegas, executives of PCB and EMS companies will meet to discuss solutions facing their industries. The PCB Executive Management Meeting and the EMS Management Council Meeting will take place March 31, 2008, at Mandalay Bay Resort & Convention Center.



These two customized, full-day programs feature experts who will provide in-depth information on critical management topics facing the EMS and PCB industries.

During the EMS Management Council Meeting, speakers will address: best practices of managing customer relationships, the five key elements that should be in an EMS contract, and how to cope with the counterfeit component problem. In addition, a panel of experts will present the pros and cons of securing growth funding from investment banking, commercial banking and private equity investment firms; and another multi-focused panel will discuss best practices in human resources management, including an update on U.S. federal employment law.

At the PCB Executive Management Meeting, attendees will focus on strategic planning to take advantage of new opportunities in the PCB industry. **Rex Rosario**, chairman of **Graphics PLC**, will share what he learned during the development of the Graphics PLC/SOMACIS joint venture in China. **Dr. Greg Munie**, chairman of the IPC technical conference, will provide an

overview of the latest technological advancements so executives can guide their companies in the right direction. **Joe Fjelstad** of **SiliconPipe, Inc.** will explain how Occam will impact the industry. There will also be a session on the best proven methods for developing strategies in the PCB industry.

The exclusive nature of the meetings enables candid roundtable discussions and provides value through peer experience and advice. "Every year that I attend PCB Executive Management Meeting, I come away with ideas to improve our process, solutions to address specific problems and a better understanding of what to expect from our customers and suppliers," said **David Smart**, president, **Enigma Interconnect Inc.**, British Columbia.

The IPC EMS and PCB Executive Management Meetings are open to both members and nonmembers, but registrants must hold senior level positions with an EMS or PCB company to attend.

For more information on the management meetings or to register, visit www.GoIPCShows.org or contact Susan Filz, IPC director of industry programs, at +1 847-597-2884 or SusanFilz@ipc.org.

Hall of Fame Award

Robert Neves To Receive IPC'S 2007 Hall Of Fame Award

(continued from page 1)

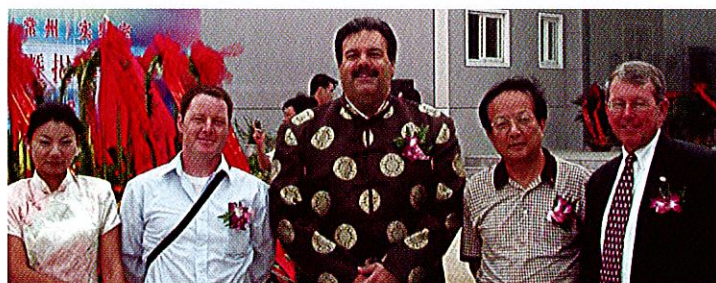
Additionally, along with fellow Hall of Fame members **Dieter Bergman** and **Doug Sober**, Neves has represented the U.S. and IPC internationally at IEC meetings, and served as Convenor of Working Group 10 (test methods) of the IEC Technical Committee driving standardization in electronics assembly technology (TC 52/TC 91) for 10 years.

Committing the resources of his time and company, Neves involved Microtek in several IPC test programs. He has played an active role in IPC long-range planning and roadmapping sessions and has been a staunch supporter of the educational mission of IPC, serving as a workshop and tutorial instructor. Both of Microtek's facilities are certified IPC-A-600 training centers.

Neves began his career 25 years ago as a drill inspector, working his way up to quality engineer. In 1985, he became interested in PCB testing and formed Microtek Labs with a partner. The company now has offices in Anaheim, Calif., and Changzhou, China. According to Neves, "A strong desire to learn as much as I could about the industry led me to extensive involvement in industry programs. I saw that

participation in IPC standardization efforts was vital to both personal and business growth."

When asked about his thoughts as he looks to the future of the industry, Neves says, "I have committed to helping TGAsia, the new IPC committee group in China, for terms and definitions, assembly and joining, and product assurance. As IPC's mission is global, I want to make sure I can pass on some of what I have learned and experienced." ◀



Bob Neves (center) at Microtek grand opening in China